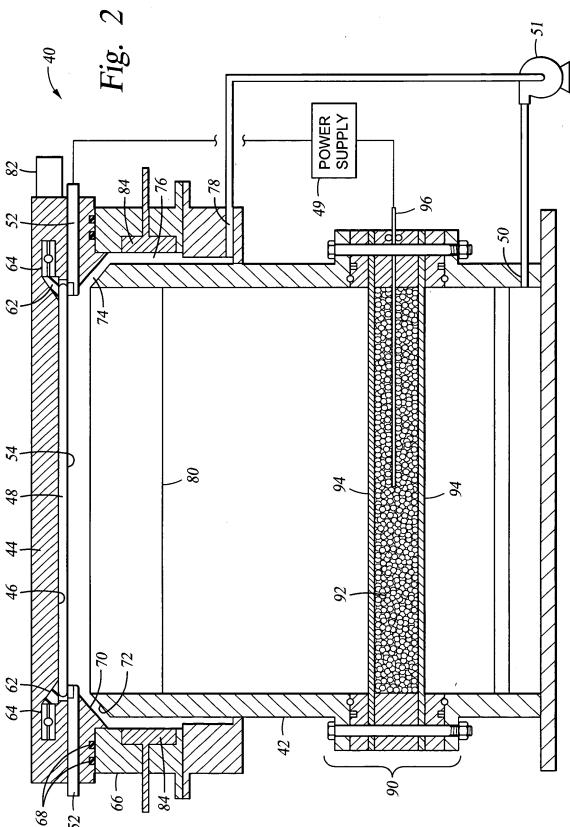
ATTY DKT. NO.: AMAT/2601 R 02/CMP/ECP/RKK
U.S. PATENT NO.: 6,261,433 CONF. NO.: N/A
ISSUED: JULY 17, 2001
APPLICANT: APPLIED MATERIALS
TITLE: ELECTRO-CHEMICAL DEPOSITION SYSTEM AND METHOD OF **ELECTROPLATING ON SUBSTRATES** INVENTOR: UZIEL LANDAU. EXPRESS MAIL NO.: EV331233581US PAGE 1 OF 7 1/7 - 10 32 38 34 Fig. 1A 32 (PRIOR ART) 15 *30* - 10 20 Fig. 1B - 16 (PRIOR ART) - 10 Fig. 1C -16 18 (PRIOR ART) 15 - 10 Fig. 1D -16 (PRIOR ART) 21 20 - 10 Fig. 1E -16 (PRIOR ART) L

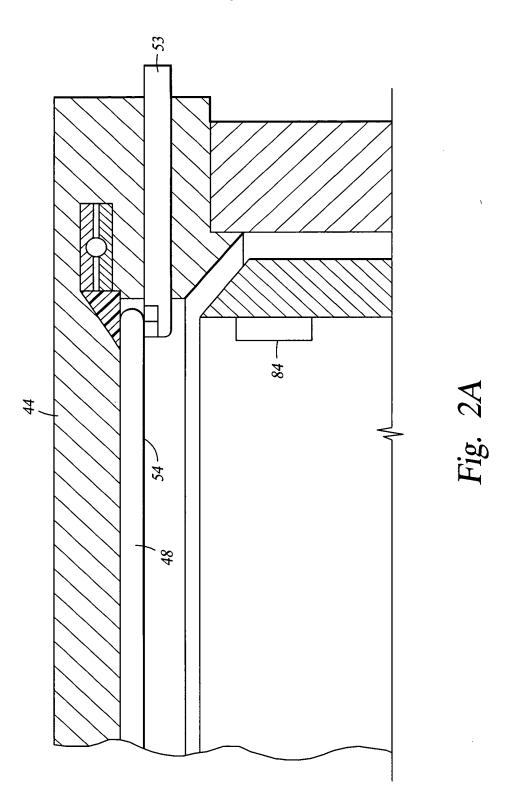
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EXPRESS MAIL NO.: EV331233581US PAGE 4 OF 7

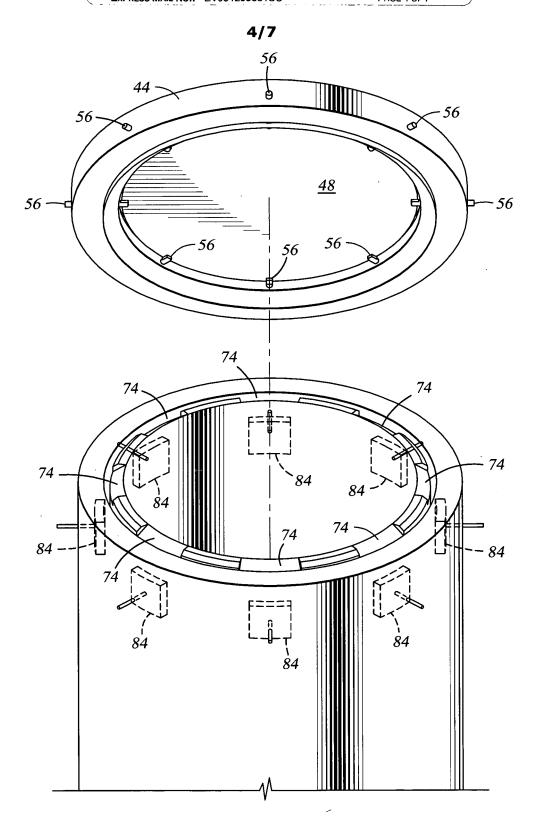
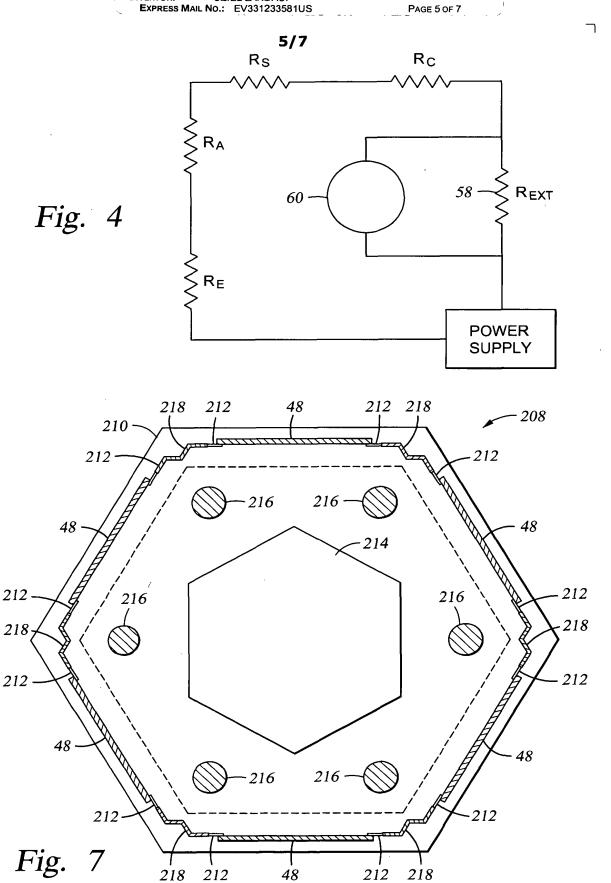


Fig. 3

ATTY DKT. NO.: AMAT/2601 R 02/CMP/ECP/RKK
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INVENTOR: UZIEL LANDAU.
EXPRESS MAIL NO.: EV331233581US PAGE 5 OF 7



ATTY DKT. NO.: AMAT/2601 R 02/CMP/ECP/RKK
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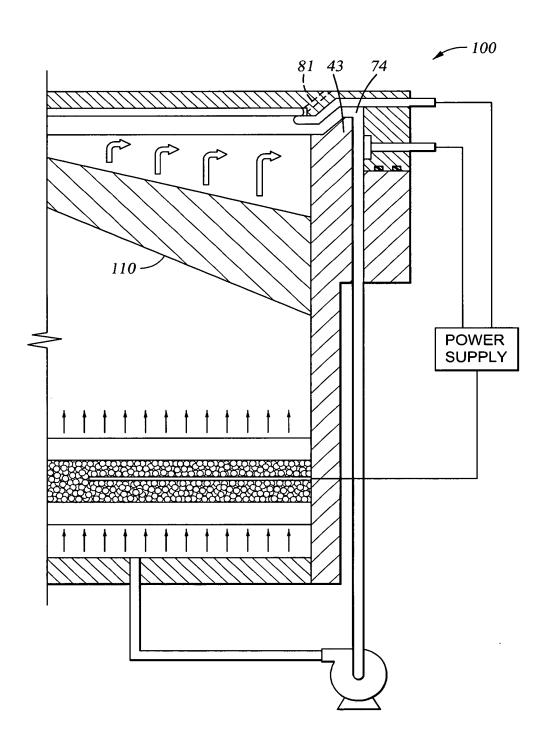


Fig. 5

ATTY DKT. NO.: AMAT/2601 R 02/CMP/ECP/RKK
U.S. PATENT NO.: 6,261,433 CONF. NO.: N/A
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INVENTOR: UZIEL LANDAU. EXPRESS MAIL No.: EV331233581US

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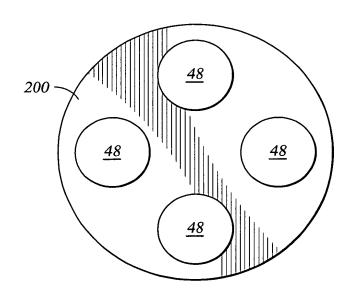


Fig. 6A

